

# CYCOLOY™ RESIN XCY630

REGION ASIA

## DESCRIPTION

PC/ABS, hydrolytically stable.

## TYPICAL PROPERTY VALUES

Revision 20180905

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
<b>MECHANICAL</b>			
Tensile Stress, yld, Type I, 50 mm/min	54	MPa	ASTM D 638
Tensile Stress, brk, Type I, 50 mm/min	53	MPa	ASTM D 638
Tensile Strain, yld, Type I, 50 mm/min	4.5	%	ASTM D 638
Tensile Strain, brk, Type I, 50 mm/min	120	%	ASTM D 638
Tensile Modulus, 5 mm/min	2300	MPa	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	89	MPa	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	2300	MPa	ASTM D 790
Tensile Stress, yield, 50 mm/min	54	MPa	ISO 527
Tensile Stress, break, 50 mm/min	53	MPa	ISO 527
Tensile Strain, yield, 50 mm/min	4.5	%	ISO 527
Tensile Strain, break, 50 mm/min	120	%	ISO 527
Tensile Modulus, 1 mm/min	2250	MPa	ISO 527
Flexural Stress, yield, 2 mm/min	82	MPa	ISO 178
Flexural Modulus, 2 mm/min	2200	MPa	ISO 178
<b>IMPACT</b>			
Izod Impact, notched, 23°C	590	J/m	ASTM D 256
Izod Impact, notched, -30°C	430	J/m	ASTM D 256
Instrumented Impact Total Energy, 23°C	55	J	ASTM D 3763
Instrumented Impact Total Energy, -30°C	67	J	ASTM D 3763
Izod Impact, notched 80*10*3 +23°C	65	kJ/m <sup>2</sup>	ISO 180/1A
Izod Impact, notched 80*10*3 -30°C	30	kJ/m <sup>2</sup>	ISO 180/1A
Charpy 23°C, V-notch Edgew 80*10*3 sp=62mm	65	kJ/m <sup>2</sup>	ISO 179/1eA
Charpy -30°C, V-notch Edgew 80*10*3 sp=62mm	30	kJ/m <sup>2</sup>	ISO 179/1eA
<b>THERMAL</b>			
Vicat Softening Temp, Rate B/50	126	°C	ASTM D 1525
HDT, 1.82 MPa, 3.2mm, unannealed	107	°C	ASTM D 648
CTE, -40°C to 40°C, flow	7.E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	7.E-05	1/°C	ASTM E 831
Thermal Conductivity	0.2	W/m-°C	ISO 8302
CTE, -40°C to 40°C, flow	8.E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	8.E-05	1/°C	ISO 11359-2
Ball Pressure Test, 75°C +/- 2°C	Pass	-	IEC 60695-10-2
Vicat Softening Temp, Rate B/50	126	°C	ISO 306
Vicat Softening Temp, Rate B/120	127	°C	ISO 306
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	126	°C	ISO 75/Bf

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	105	°C	ISO 75 /Af
<b>PHYSICAL</b>			
Specific Gravity	1.14	-	ASTM D 792
Mold Shrinkage, flow, 3.2 mm	0.5 – 0.7	%	SABIC method
Mold Shrinkage, xflow, 3.2 mm	0.5 – 0.7	%	SABIC method
Melt Flow Rate, 260°C/5.0 kgf	26	g/10 min	ASTM D 1238
Density	1.14	g/cm <sup>3</sup>	ISO 1183
Water Absorption, (23°C/sat)	0.4	%	ISO 62
Moisture Absorption (23°C / 50% RH)	0.15	%	ISO 62
Melt Volume Rate, MVR at 260°C/5.0 kg	22	cm <sup>3</sup> /10 min	ISO 1133
Melt Viscosity, 260°C, 1500 sec-1	170	Pa-s	ISO 11443
<b>ELECTRICAL</b>			
Volume Resistivity	>1.E+15	Ohm-cm	IEC 60093
Surface Resistivity, ROA	>1.E+15	Ohm	IEC 60093
Dielectric Strength, in oil, 0.8 mm	35	kV/mm	IEC 60243-1
Dielectric Strength, in oil, 1.6 mm	25	kV/mm	IEC 60243-1
Dielectric Strength, in oil, 3.2 mm	17	kV/mm	IEC 60243-1
<b>INJECTION MOLDING</b>			
Drying Temperature	95 – 105	°C	
Drying Time	2 – 4	hrs	
Maximum Moisture Content	0.02	%	
Melt Temperature	260 – 290	°C	
Nozzle Temperature	240 – 280	°C	
Front - Zone 3 Temperature	250 – 290	°C	
Middle - Zone 2 Temperature	250 – 290	°C	
Rear - Zone 1 Temperature	230 – 260	°C	
Hopper Temperature	60 – 80	°C	
Mold Temperature	60 – 90	°C	

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